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PATENT
Attorney Docket No.: COOL-02100

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	Group Art Unit: 3753
Douglas Werner et al.)	Examiner:
Serial No.: 10/769,717)	<u>TRANSMITTAL LETTER</u>
Filed: January 29, 2004)	162 N. Wolfe Road
For: HERMETIC CLOSED LOOP)	Sunnyvale, CA 94086
FLUID SYSTEM)	(408) 530-9700
)	Customer No.: 28960

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

Enclosed please find an Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

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The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 7-14-04

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CERTIFICATE OF MAILING (37 CFR § 1.8(a))

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #200407141632055371570343502050701044); (EFS ID #64520); and (EFS ID #64521). Applicants have become aware of the following printed publication which may be material to the examination of this application:

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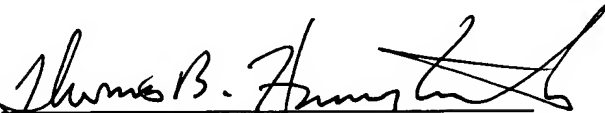
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This Information Disclosure Statement under 37 C.F.R. §§ 1.56 and 1.97 is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that anyone or more of these citations constitutes prior art.

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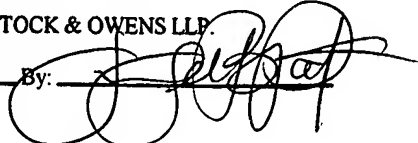
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(Modified)U.S. Department of Commerce
Patent and Trademark Office

Attorney Docket No.: COOL-02100

Serial No.: 10/769,717

INFORMATION DISCLOSURE STATEMENT BY APPLICANT
(Use Several Sheets If Necessary)

Applicants: Douglas Werner et al.

(37 CFR § 1.98(b))

Filing Date: January 29, 2004

Group Art Unit: 3753

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OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)					
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Title of Invention

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Application Number:	10/769717 *10/769717*						
Date:	2004-01-29						
First Named Applicant:	Douglas Werner						
Confirmation Number:	8804						
Attorney Docket Number:							
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Documents being submitted	Files
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Application Number:	10/769717						
Confirmation Number:	8804						
First Named Applicant:	Douglas Werner						
Attorney Docket Number:							
Search string:	(3654988 or 3817321 or 3823572 or 3923426 or 3929154 or 4109707 or 4194559 or 4248295 or 4485429 or 4561040 or 4664181 or 4866570 or 4894709 or 4896719 or 4908112 or 5009760 or 5058627 or 5070040 or 5088005 or 5096388 or 5099311 or 5099910 or 5125451 or 5131233 or 5203401 or 5218515 or 5219278 or 5232047 or 5239200 or 5263251 or 5274920 or 5309319 or 5317805 or 5325265 or 5336062 or 5380956 or 5383340 or 5427174 or 5436793 or 5514906 or 5544696 or 5548605 or 5579828 or 5585069 or 5641400 or 5692558 or 5696405 or 5703536 or 5704416 or 5727618).pn.						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	3654988	1972-04-11	Clayton, III			
	2	3817321	1974-06-18	von Cube et al.			
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Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Title of Invention	HERMETIC CLOSED LOOP FLUID SYSTEM									
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Thomas B. Haverstock Registered Number: 32571</td><td>/tbh/</td><td>Attorney</td></tr></tbody></table>		Submitted by:	Elec. Sign.	Sign. Capacity	Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney
Submitted by:	Elec. Sign.	Sign. Capacity					
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us-ids	COOL02100C-usidst.xml us-ids.dtd us-ids.xsl
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Title of Invention	HERMETIC CLOSED LOOP FLUID SYSTEM						
Application Number:	10/769717						
Confirmation Number:	8804						
First Named Applicant:	Douglas Werner						
Attorney Docket Number:							
Search string:	(6313992 or 6317326 or 6321791 or 6322753 or 6324058 or 6351384 or 6337794 or 6388317 or 6400012 or 6406605 or 6415860 or 6416642 or 6417060 or 6424531 or 6443222 or 6444461 or 6457515 or 6495015 or 6537437 or 6543521 or 6553253 or 6572749 or 6588498 or 6591625 or 6632655 or 20010016985 or 20010024820 or 20010044155 or 20010045270 or 20010046703 or 20010055714 or 20020011330).pn.						
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US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	6317326	2001-11-13	Vogel et al.	B1		
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Signature

Examiner Name	Date

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